

# SOT638-2

plastic thermal enhanced thin quad flat package; 100 leads;  
body 14 x 14 x 1 mm; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HTQFP100
<b>Package type industry code</b>	HTQFP100
<b>Package style descriptive code</b>	HTQFP (thermal enhanced thin quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-2-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height	0.95	-	1	1.05	mm
n <sub>2</sub>	actual quantity of termination	-	-	100	-	



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## 2. Package outline

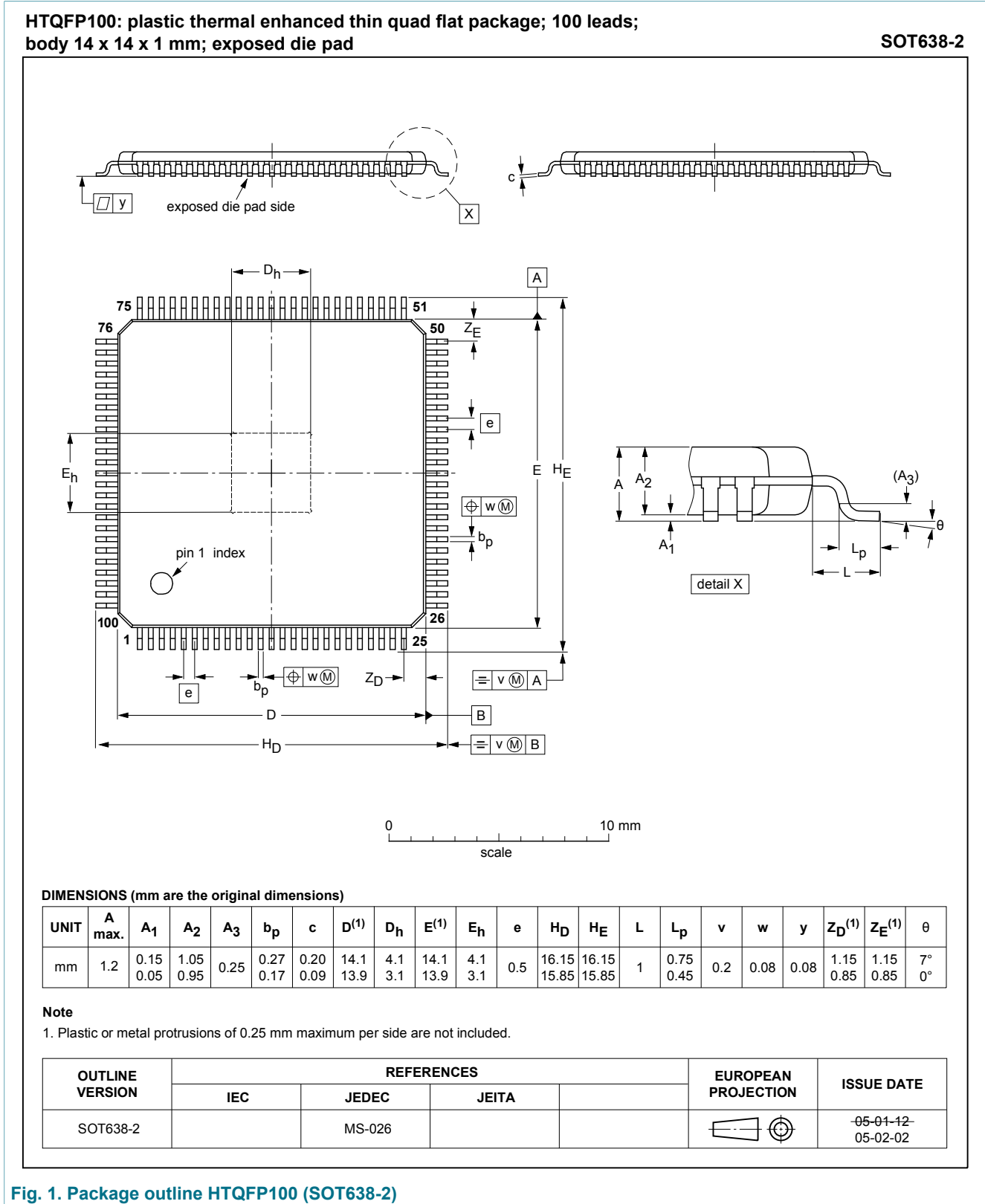


Fig. 1. Package outline HTQFP100 (SOT638-2)

### 3. Soldering

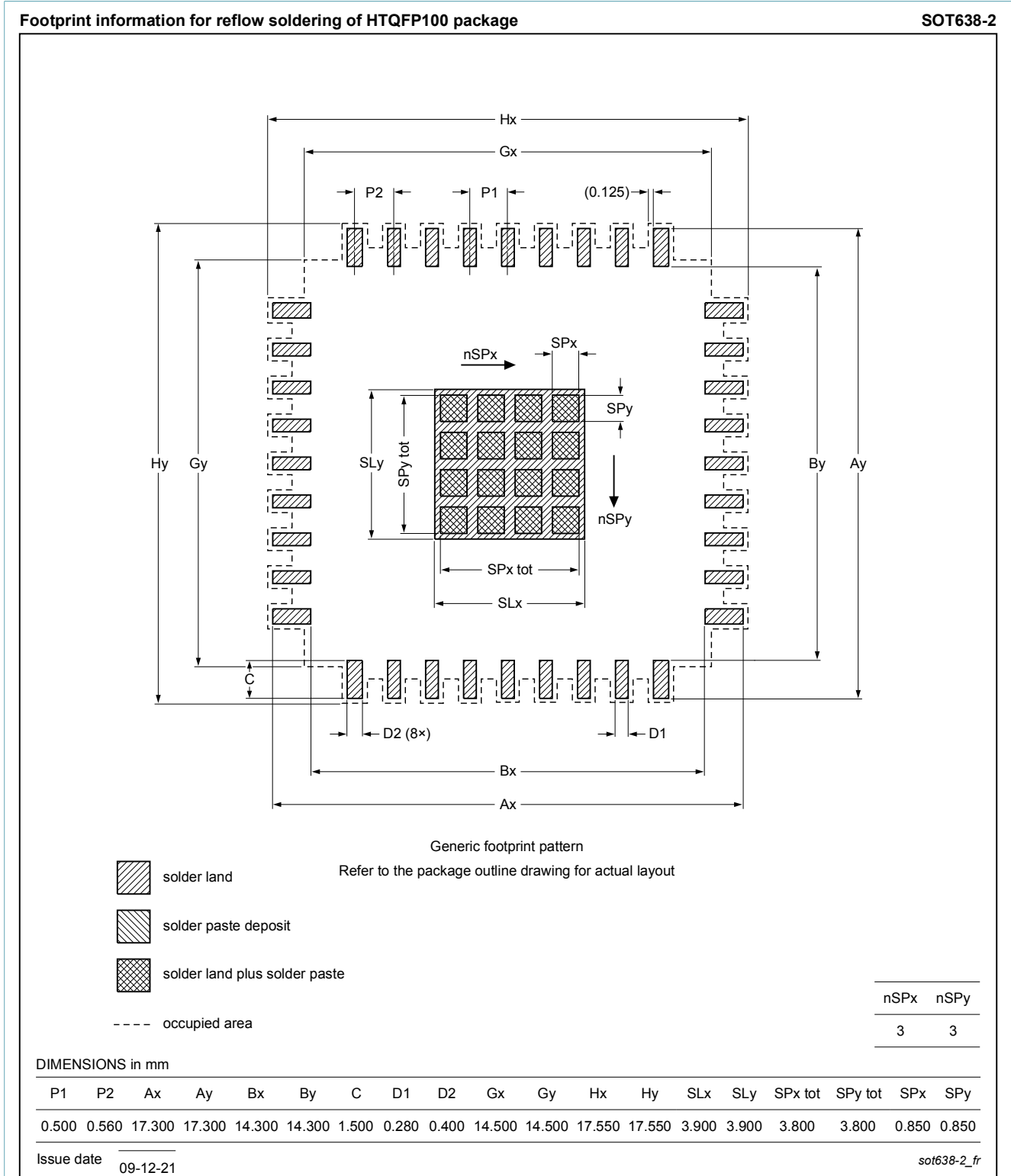


Fig. 2. Reflow soldering footprint for HTQFP100 (SOT638-2)

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## 4. Legal information

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